

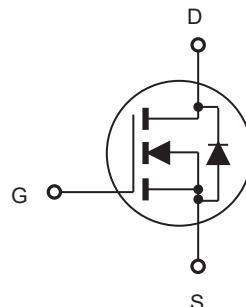


# CEP38N65S/CEB38N65S CEF38N65S

## N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

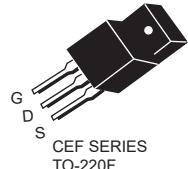
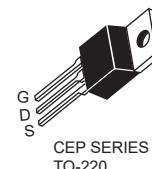
Type	V <sub>DSS</sub>	R <sub>DS(ON)</sub>	I <sub>D</sub>	@V <sub>GS</sub>
CEP38N65S	650V	0.1Ω	38A	10V
CEB38N65S	650V	0.1Ω	38A	10V
CEF38N65S	650V	0.1Ω	38A <sup>d</sup>	10V



- Super high dense cell design for extremely low R<sub>DS(ON)</sub>.
- High power and current handing capability.
- RoHS compliant.
- Fast reverse recovery time(Trr).
- Drive circuits can be simple.

### APPLICATIONS

- Sever and telecom power supplies.
- String PV inverters.



### ABSOLUTE MAXIMUM RATINGS

 T<sub>C</sub> = 25°C unless otherwise noted

Parameter	Symbol	Limit		Units
		TO-220/263	TO-220F	
Drain-Source Voltage	V <sub>DS</sub>	650		V
Gate-Source Voltage	V <sub>GS</sub>	±30		V
Drain Current-Continuous @ T <sub>C</sub> = 25°C @ T <sub>C</sub> = 100°C	I <sub>D</sub>	38	38 <sup>d</sup>	A
		24	24 <sup>d</sup>	A
Drain Current-Pulsed <sup>a</sup>	I <sub>DM</sub> <sup>e</sup>	152	152 <sup>d</sup>	A
Maximum Power Dissipation @ T <sub>C</sub> = 25°C - Derate above 25°C	P <sub>D</sub>	357	89	W
		2.8	0.7	W/°C
Single Pulsed Avalanche Energy <sup>h</sup>	E <sub>AS</sub>	960		mJ
Single Pulsed Avalanche Current <sup>h</sup>	I <sub>AS</sub>	8		A
Operating and Store Temperature Range	T <sub>J,T<sub>stg</sub></sub>	-55 to 150		°C

### Thermal Characteristics

Parameter	Symbol	Limit		Units
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	0.35	1.4	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	62.5	65	°C/W



# CEP38N65S/CEB38N65S

## CEF38N65S

### Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Test Condition	Min	Typ	Max	Units
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}} = 0\text{V}, I_D = 250\mu\text{A}$	650			V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}} = 650\text{V}, V_{\text{GS}} = 0\text{V}$			5	$\mu\text{A}$
Gate Body Leakage Current, Forward	$I_{\text{GSSF}}$	$V_{\text{GS}} = 30\text{V}, V_{\text{DS}} = 0\text{V}$			100	nA
Gate Body Leakage Current, Reverse	$I_{\text{GSSR}}$	$V_{\text{GS}} = -30\text{V}, V_{\text{DS}} = 0\text{V}$			-100	nA
<b>On Characteristics<sup>b</sup></b>						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{GS}} = V_{\text{DS}}, I_D = 250\mu\text{A}$	2.5		4.5	V
Static Drain-Source On-Resistance	$R_{\text{DS}(\text{on})}$	$V_{\text{GS}} = 10\text{V}, I_D = 20\text{A}$		0.085	0.1	$\Omega$
<b>Dynamic Characteristics<sup>c</sup></b>						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}} = 150\text{V}, V_{\text{GS}} = 0\text{V}, f = 1.0 \text{ MHz}$		2425		pF
Output Capacitance	$C_{\text{oss}}$			120		pF
Reverse Transfer Capacitance	$C_{\text{rss}}$			0.8		pF
<b>Switching Characteristics<sup>c</sup></b>						
Turn-On Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}} = 520\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}, R_{\text{GEN}} = 6\Omega$		39		ns
Turn-On Rise Time	$t_r$			14		ns
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$			88		ns
Turn-Off Fall Time	$t_f$			4		ns
Total Gate Charge	$Q_g$	$V_{\text{DS}} = 520\text{V}, I_D = 20\text{A}, V_{\text{GS}} = 10\text{V}$		68		nC
Gate-Source Charge	$Q_{\text{gs}}$			15		nC
Gate-Drain Charge	$Q_{\text{gd}}$			27		nC
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Drain-Source Diode Forward Current	$I_s$ <sup>f</sup>				38	A
Drain-Source Diode Forward Voltage <sup>b</sup>	$V_{\text{SD}}$	$V_{\text{GS}} = 0\text{V}, I_s = 20\text{A}$ <sup>g</sup>			1.5	V
Reverse Recovery Time	$T_{\text{rr}}$	$V_R = 50\text{V}, I_F = 20\text{A}, dI_F/dt = 100\text{A/us}$		206		ns
Reverse Recovery Charge	$Q_{\text{rr}}$			1.52		$\mu\text{C}$

Notes :

- a.Repetitive Rating : Pulse width limited by maximum junction temperature .
- b.Pulse Test : Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$  .
- c.Guaranteed by design, not subject to production testing.
- d.Limited only by maximum temperature allowed .
- e.Pulse width limited by safe operating area .
- f.Full package  $I_{\text{S}(\text{max})} = 19\text{A}$  .
- g.Full package  $V_{\text{SD}}$  test condition  $I_s = 19\text{A}$  .
- h. $L = 30\text{mH}, I_{\text{AS}} = 8\text{A}, V_{\text{DD}} = 60\text{V}, R_G = 25\Omega$ , Starting  $T_J = 25^\circ\text{C}$ .



# CEP38N65S/CEB38N65S CEF38N65S

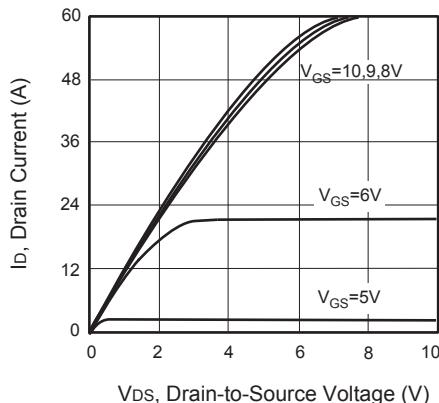


Figure 1. Output Characteristics

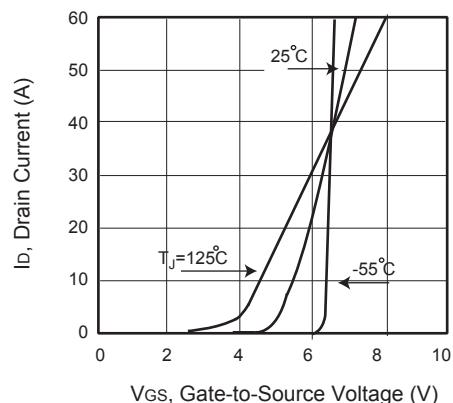


Figure 2. Transfer Characteristics

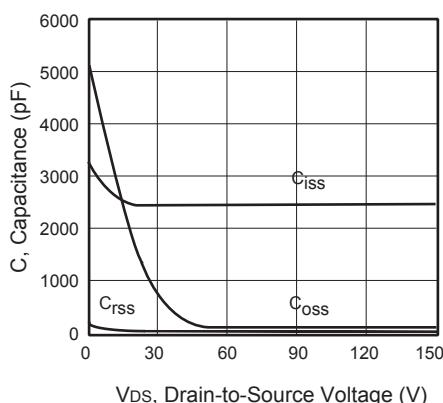


Figure 3. Capacitance

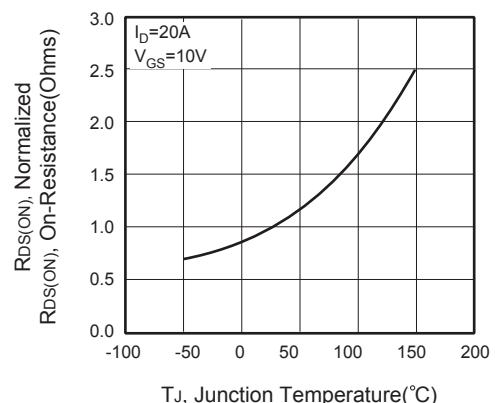


Figure 4. On-Resistance Variation with Temperature

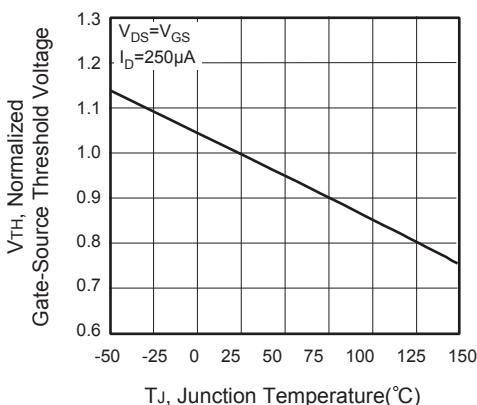


Figure 5. Gate Threshold Variation with Temperature

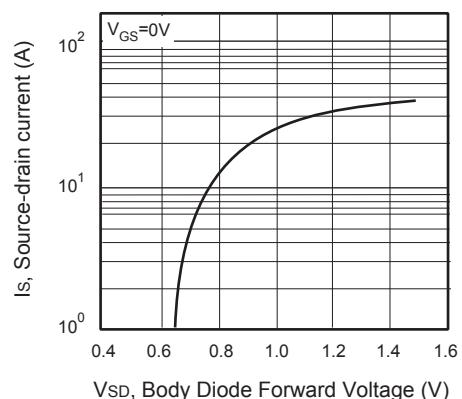


Figure 6. Body Diode Forward Voltage Variation with Source Current



# CEP38N65S/CEB38N65S CEF38N65S

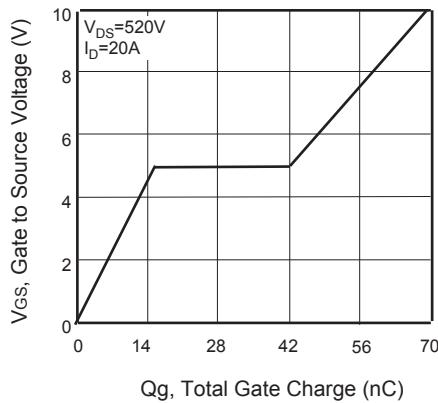


Figure 7. Gate Charge

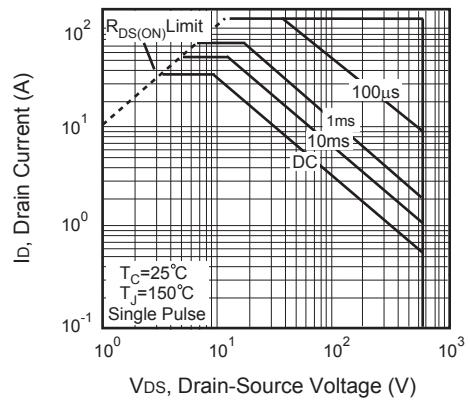


Figure 8. Maximum Safe  
Operating Area

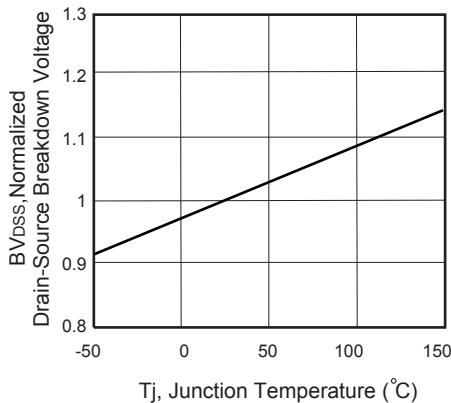


Figure 9. Breakdown Voltage Variation  
VS Temperature

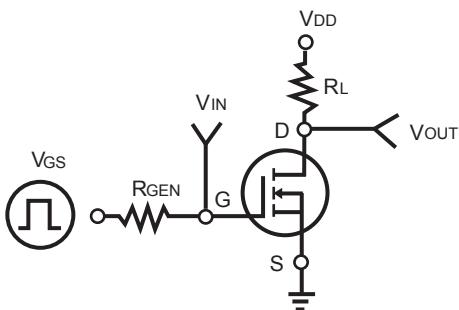


Figure 10. Switching Test Circuit

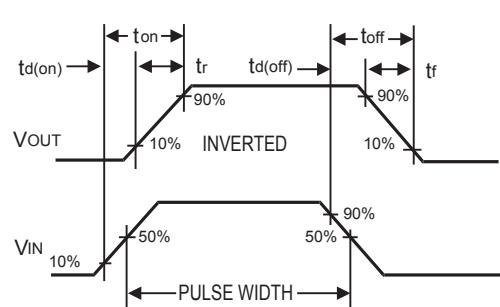


Figure 11. Switching Waveforms



# CEP38N65S/CEB38N65S CEF38N65S

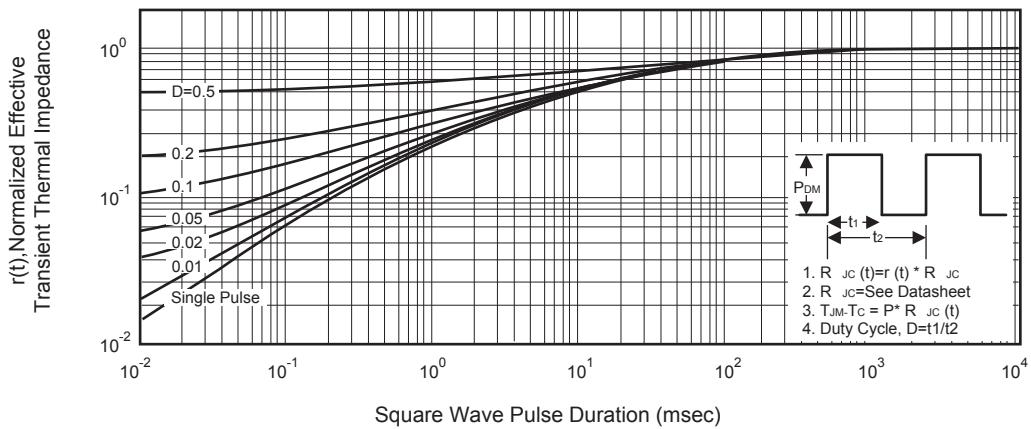


Figure 12. Normalized Thermal Transient Impedance Curve